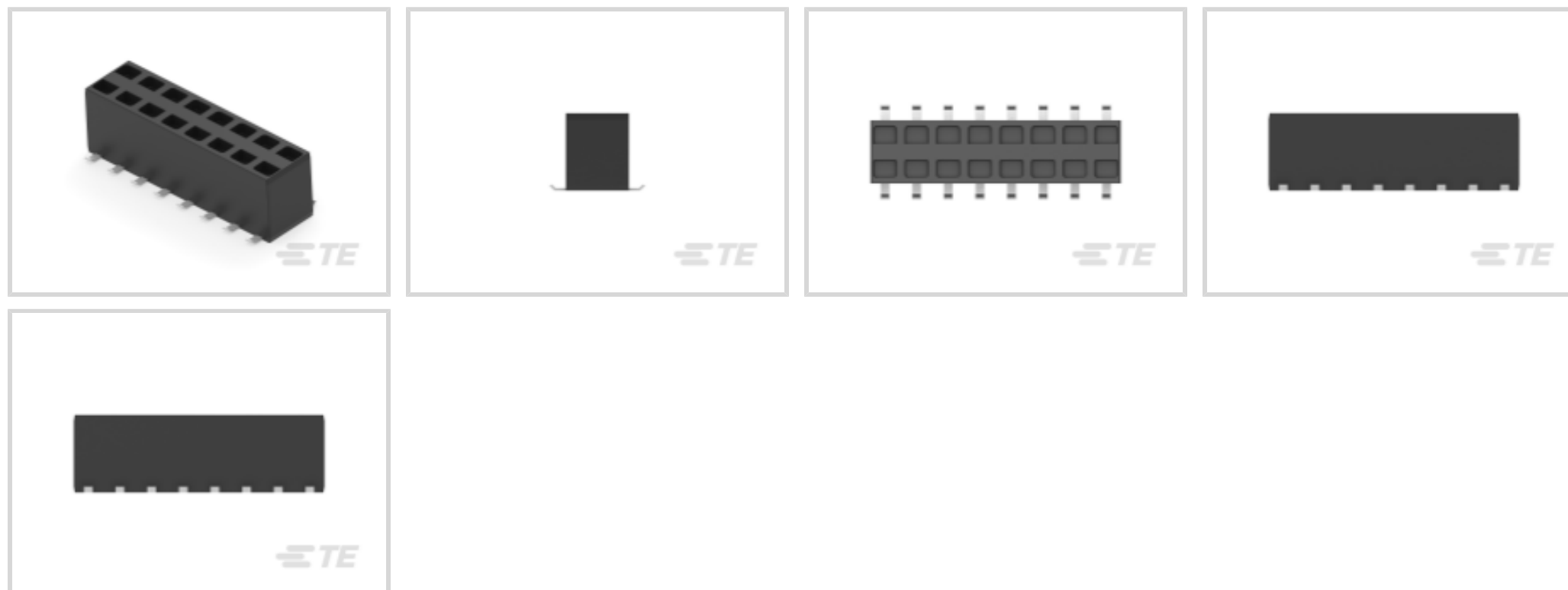




Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **16**

Centerline (Pitch): **2.54 mm [.1 in]**

### Features

#### Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

#### Configuration Features

Number of Rows	2
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	16
Board-to-Board Configuration	Parallel

#### Body Features

Connector Profile	Standard
-------------------	----------

#### Contact Features

Contact Layout	Inline
----------------	--------



Contact Protection Type	Closed Entry Housing
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2.5 $\mu$ m
Mating Pin Diameter	.63 mm[.025 in]
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 $\mu$ m[30 $\mu$ in]
Contact Type	Socket
Contact Current Rating (Max)	3 A

#### Termination Features

Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.7 mm[.027 in]
Termination Method to Printed Circuit Board	Surface Mount

#### Mechanical Attachment

Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

#### Housing Features

Mating Entry Location	Bottom & Top
Centerline (Pitch)	2.54 mm[.1 in]
Housing Color	Black
Housing Material	LCP (Liquid Crystal Polymer)

#### Dimensions

Connector Height	6.2 mm[.244 in]
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	9 mm[.354 in]
PCB Thickness (Recommended)	1.6 mm[.063 in]

#### Usage Conditions

Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
-----------------------------	----------------------------

#### Operation/Application



Solder Process Feature	Board Standoff
------------------------	----------------

Circuit Application	Signal
---------------------	--------

### Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

### Packaging Features

Packaging Quantity	600
--------------------	-----

Packaging Method	Reel
------------------	------

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
------------------------------	-----------

EU ELV Directive 2000/53/EC	Compliant
-----------------------------	-----------

China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
---	---

EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUL 2021 (219) Candidate List Declared Against: JUN 2020 (209) SVHC > Threshold: Not Yet Reviewed
--	---

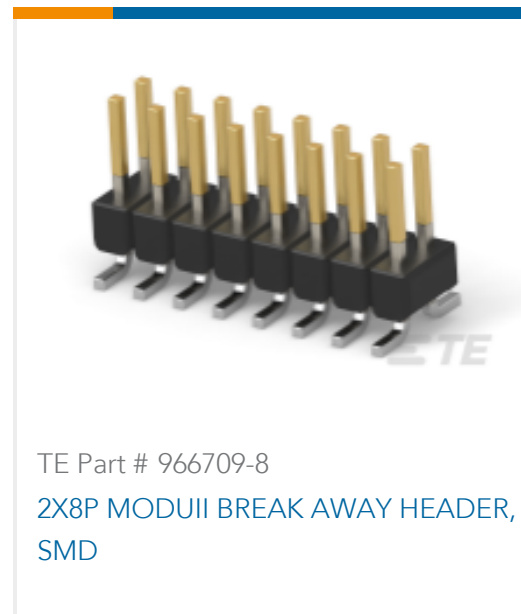
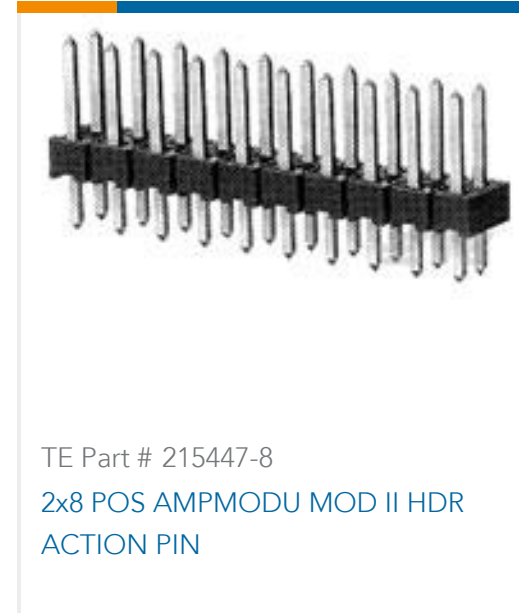
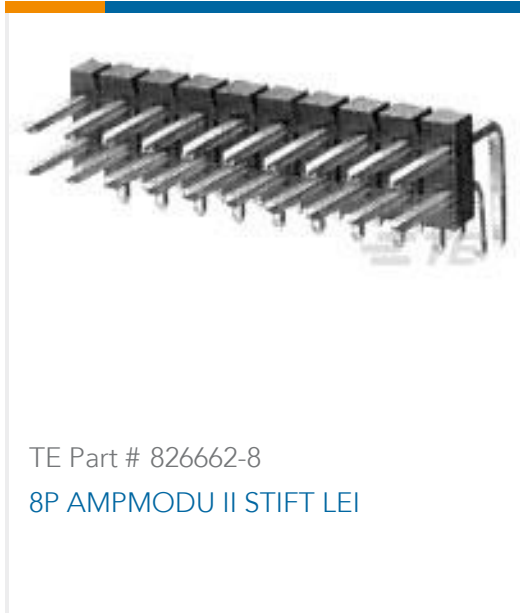
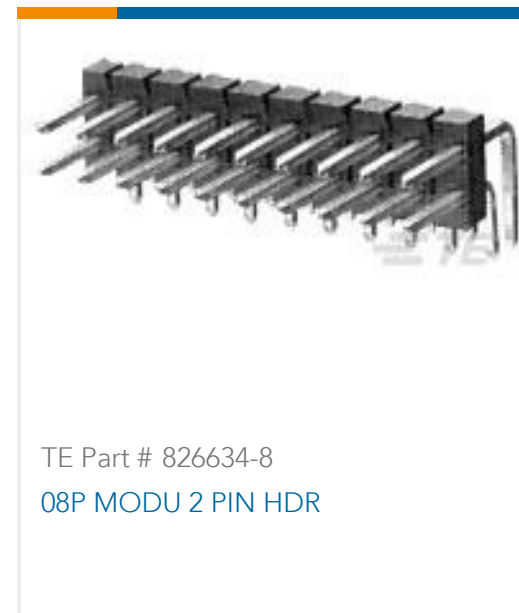
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
-----------------	---

Solder Process Capability	Reflow solder capable to 260°C
---------------------------	--------------------------------

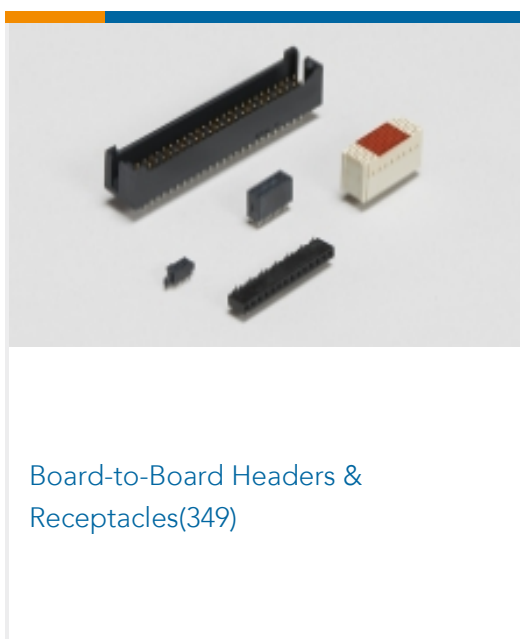
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

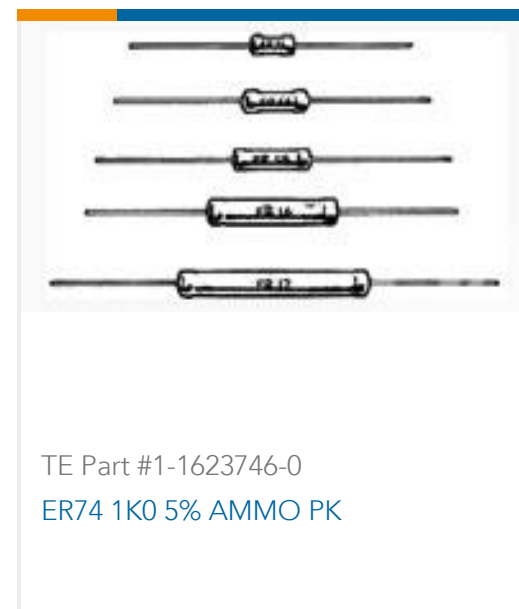
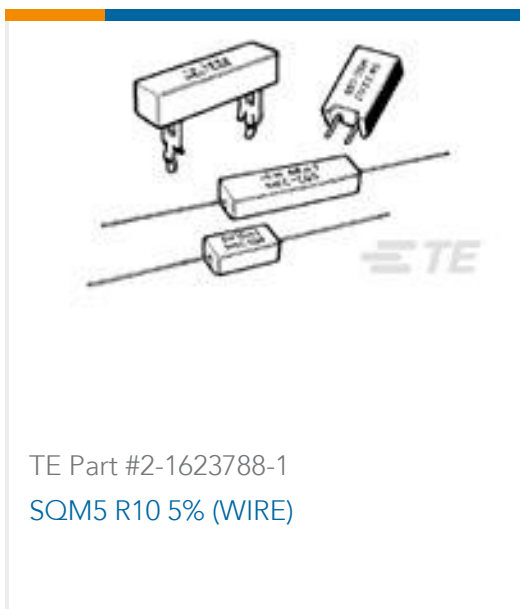
### Compatible Parts



Also in the Series | **AMPMODU HV-100/HV-190**



Customers Also Bought





## Documents

### Product Drawings

[2x8P HV100 REC. CON, SMD, GOLD, BLISTER](#)

English

### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_969973-8\\_E.2d\\_dxf.zip](#)

English

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_969973-8\\_E.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_969973-8\\_E.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Environmental Compliance

[MD\\_969973-8\\_07212017043\\_dmtec](#)

English

[MD\\_969973-8\\_07212017043\\_dmtec](#)

English